

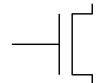
Lecture 3: CMOS Transistor Theory

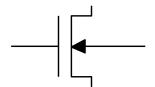
Outline

- Introduction
- MOS Capacitor
- nMOS I-V Characteristics
- pMOS I-V Characteristics
- ☐ Gate and Diffusion Capacitance

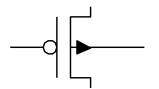
Introduction

- ☐ So far, we have treated transistors as ideal switches
- ☐ An ON transistor passes a finite amount of current
 - Depends on terminal voltages
 - Derive current-voltage (I-V) relationships
- ☐ Transistor gate, source, drain all have capacitance
 - $-I = C (\Delta V/\Delta t) \rightarrow \Delta t = (C/I) \Delta V$
 - Capacitance and current determine speed









MOS Capacitor

 $V_q < 0$

(a)

 $V_a > V_t$

(c)

- ☐ Gate and body form MOS capacitor
- Operating modes
 - Accumulation
 - Depletion
 - Inversion
- ☐ Threshold voltage
 is when inversion
 begins

polysilicon gate silicon dioxide insulator p-type body

depletion region

inversion region depletion region depletion region

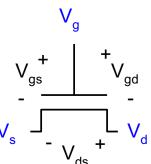
Terminal Voltages

 \square Mode of operation depends on V_g , V_d , V_s

$$-V_{gs} = V_g - V_s$$

$$-V_{gd} = V_g - V_d$$

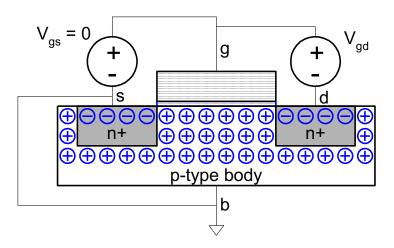
$$-V_{ds} = V_{d} - V_{s} = V_{gs} - V_{gd}$$



- Source and drain are symmetric diffusion terminals
 - By convention, source is terminal at lower voltage
 - Hence V_{ds} ≥ 0
- nMOS body is grounded. First assume source is 0 too.
- ☐ Three regions of operation
 - Cutoff
 - Linear
 - Saturation

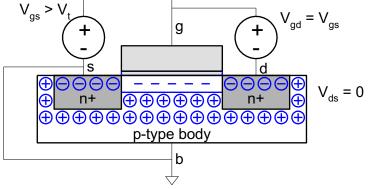
nMOS Cutoff

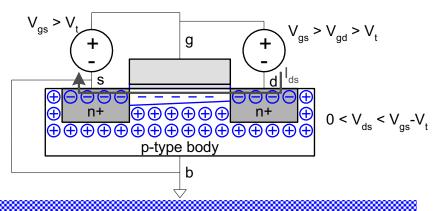
- \Box $V_{gs} < V_t$
- No inversion, no channel
- \Box $I_{ds} \approx 0$



nMOS Linear

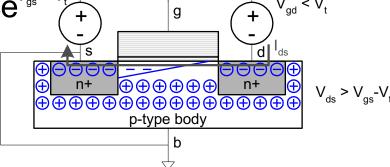
- \Box $V_{gs} > V_t$
- □ But V_{ds} small
- □ Channel forms
- Current flows from d to s
 - e- from s to d
- \Box I_{ds} increases with V_{ds}
- ☐ Similar to linear resistor





nMOS Saturation

- \Box $V_{qs} > V_t$
- \Box $V_{ds} > V_{qs} V_{t}$
- □ Channel pinches off
- I_{ds} independent of V_{ds}
- ☐ We say current saturates

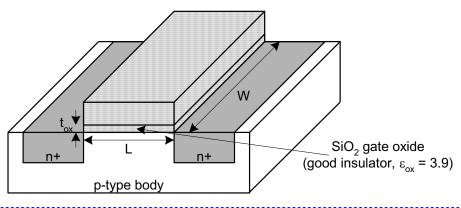


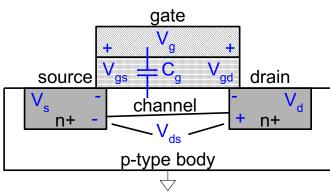
I-V Characteristics

- ☐ In Linear region, I_{ds} depends on
 - How much charge is in the channel?
 - How fast is the charge moving?

Channel Charge

- MOS structure looks like parallel plate capacitor while operating in inversions
 - Gate oxide channel
- \square Q_{channel} =





Carrier velocity

- ☐ Charge is carried by e-
- □ Electrons are propelled by the lateral electric field between source and drain
 - -E=
- ☐ Carrier velocity *v* proportional to lateral E-field
 - -v=
- ☐ Time for carrier to cross channel:
 - -t=

nMOS Linear I-V

- Now we know
 - How much charge Q_{channel} is in the channel
 - How much time t each carrier takes to cross

$$I_{ds} =$$

=

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nMOS Saturation I-V

- \Box If $V_{gd} < V_t$, channel pinches off near drain
 - When $V_{ds} > V_{dsat} =$
- Now drain voltage no longer increases current

$$I_{ds} =$$

<u>=</u>

nMOS I-V Summary

☐ Shockley 1st order transistor models

$$I_{ds} = \begin{cases} 0 & V_{gs} < V_t & \text{cutoff} \\ \beta \left(V_{gs} - V_t - \frac{V_{ds}}{2} \right) V_{ds} & V_{ds} < V_{dsat} & \text{linear} \\ \frac{\beta}{2} \left(V_{gs} - V_t \right)^2 & V_{ds} > V_{dsat} & \text{saturation} \end{cases}$$

Example

- We will be using a 0.6 μm process for your project
 - From AMI Semiconductor

$$- t_{ox} = 100 \text{ Å}$$

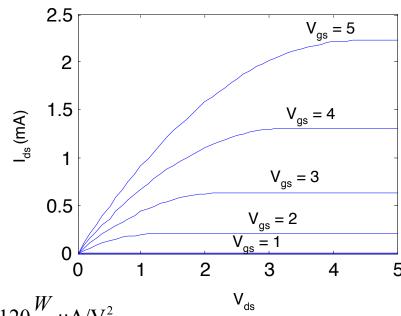
$$- \mu = 350 \text{ cm}^2/\text{V*s}$$

$$- V_t = 0.7 V$$

☐ Plot I_{ds} vs. V_{ds}

$$-V_{as} = 0, 1, 2, 3, 4, 5$$

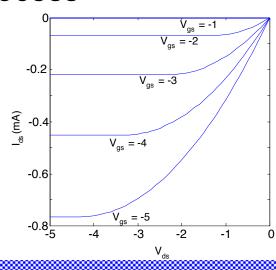
- Use W/L = 4/2 λ



$$\beta = \mu C_{ox} \frac{W}{L} = (350) \left(\frac{3.9 \times 8.85 \cdot 10^{-14}}{100 \cdot 10^{-8}} \right) \left(\frac{W}{L} \right) = 120 \frac{W}{L} \mu A/V^{2}$$

pMOS I-V

- ☐ All dopings and voltages are inverted for pMOS
 - Source is the more positive terminal
- \Box Mobility μ_p is determined by holes
 - Typically 2-3x lower than that of electrons μ_n
 - 120 cm²/V•s in AMI 0.6 μm process
 - − In advanced nodes, $\mu_p \approx \mu_n$
- ☐ Thus pMOS must be wider to provide same current
 - In this class, assume $\mu_n / \mu_p = 2$

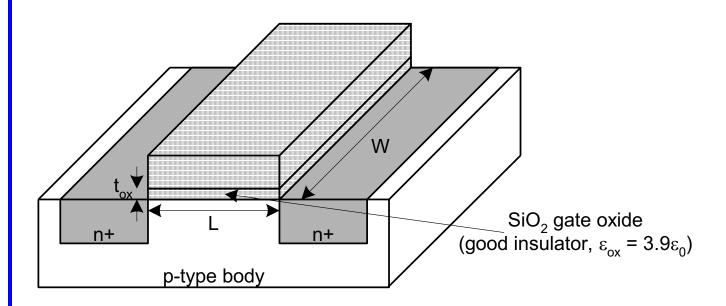


Capacitance

- □ Any two conductors separated by an insulator have capacitance
- ☐ Gate to channel capacitor is very important
 - Creates channel charge necessary for operation
- Source and drain have capacitance to body
 - Across reverse-biased diodes
 - Called diffusion capacitance because it is associated with source/drain diffusion

Gate Capacitance

- Approximate channel as connected to source
- \Box $C_{gs} = \varepsilon_{ox}WL/t_{ox} = C_{ox}WL = C_{permicron}W$
- C_{permicron} is typically about 2 fF/μm



Diffusion Capacitance

- □ Source/drain diffusion to body C_{sb}, C_{db}
- ☐ Undesirable, called *parasitic* capacitance
- ☐ Capacitance depends on area and perimeter
 - Use small diffusion nodes
 - Comparable to C_g
 for contacted diff
 - $-\frac{1}{2}C_g$ for uncontacted Source 2
 - Varies with process

